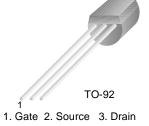


# 2N5246

# **N-Channel RF Amplifier**

- This device is designed for HF/VHF mixer/amplifier and applications where process 50is not adequate. Sufficient gain and low noise for sensitive receivers.
- Sourced from process 90.



# **Absolute Maximum Ratings\*** T<sub>a</sub>=25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{DG}$	Drain-Gate Voltage	30	V
V <sub>GS</sub>	Gate-Source Voltage	-30	V
I <sub>GF</sub>	Forward Gate Current	10	mA
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	-55 ~ 150	°C

<sup>\*</sup> This ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

## Electrical Characteristics T<sub>a</sub>=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units
Off Charac	cteristics				
V <sub>(BR)GSS</sub>	Gate-Source Breakdwon Voltage	$I_G = 1.0 \mu A, V_{DS} = 0$	-30		V
I <sub>GSS</sub>	Gate Reverse Current	$V_{GS} = 25V, V_{DS} = 0$		-1.0	nA
V <sub>GS(off)</sub>	Gate-Source Cutoff Voltage	$V_{DS} = 15V, I_{D} = 1.0nA$	-0.5	-4.0	V
On Characteristics					
I <sub>DSS</sub>	Zero-Gate Voltage Drain Current *	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0	1.5	7.0	mA
Small Signal Characteristics					
gfs	Forward Transferconductance	$V_{GS} = 0V, V_{DS} = 15V, f = 1.0kHz$	3000	9500	μmhos
goss	Common- Source Output Conductance	$V_{GS} = 0V, V_{DS} = 15V, f = 1.0kHz$		50	μmhos

<sup>\*</sup> Pulse Test: Pulse ≤ 300μs

### Thermal Characteristics T<sub>A</sub>=25°C unless otherwise noted

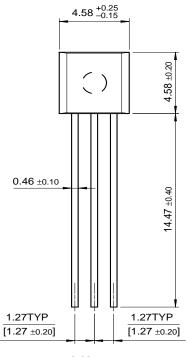
Symbol	Parameter	Max.	Units
P <sub>D</sub>	Total Device Dissipation	350	mW
	Derate above 25°C	2.8	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	°C/W

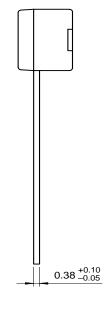
Rev. A, October 2003

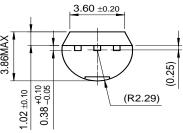
These rating are based on a maximum junction temperature of 150 degrees C.
 These are steady limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

# **Package Dimensions**

# TO-92







Dimensions in Millimeters

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The Power Franch Programmable Ac	nise™		<b>.</b>	
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### PRODUCT STATUS DEFINITIONS

### **Definition of Terms**

Datasheet Identification	Product Status	Definition
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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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